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(54) Title: PROCESS FOR HANDLING MEMS WAFERS

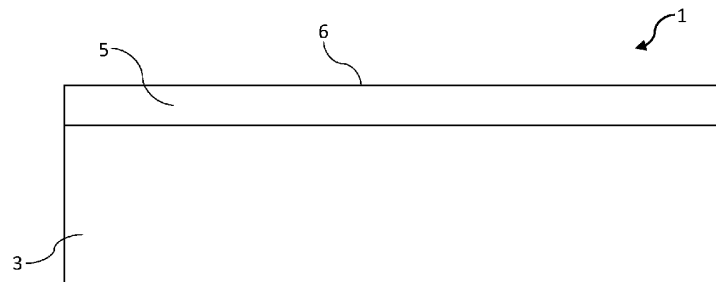


FIG. 1

(57) Abstract: A process for handling MEMS wafers includes the steps of: (i) attaching a first carrier substrate to a first side of a MEMS wafer, the first carrier substrate being attached via a first wafer bonding tape and a silicone-free peel tape, the peel tape contacting the first side of the MEMS wafer; (ii) performing wafer processing steps on an opposite second side of the MEMS wafer; (iii) releasing the first carrier substrate from the first side of the MEMS wafer via exposure to an energy source, the energy source selectively releasing the wafer bonding tape from the first side of the MEMS wafer; and (iv) peeling the peel tape away from the first side of the MEMS wafer.



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